

**Please replace the paragraph beginning at page 5, line 21, with the following rewritten paragraph:**

- (10) The process according to any one of (1) to (3), wherein said conductor layer is formed by a dry plating method.

**Please replace Table 2 beginning on line 9 of page 20 with the following Table 2:**

**[Table 2]**

	<b>Heating temp. (°C)</b>	<b>Peel strength (N/cm)</b>
<b>Ex. 2</b>	170	4.2
	220	4.4
<b>Comp. Ex. 2</b>	no	1.8

**IN THE CLAIMS:**

**Please cancel non-elected claims 14-16 without prejudice or disclaimer.**